

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) An optoelectronic component comprising a housing body and at least one semiconductor chip disposed thereon, said housing body:

having a base part comprising a connector body, on which a connecting conductor material is disposed, and

having a reflector part comprising a reflector body, on which a reflector material is disposed, wherein said reflector body comprises a ceramic,

wherein said connector body and said reflector body are preformed separately from each other and said reflector body is disposed on said connector body in the form of a reflector top.

2. (Previously presented) The optoelectronic component as in claim 1, wherein said base part and said reflector part are preformed separately from each other.

3. (Canceled)

4. (Previously presented) The optoelectronic component as in claim 1, wherein said housing body contains aluminum nitride or aluminum oxide.

5. (Previously presented) The optoelectronic component as in claim 1, wherein said connecting conductor material is different from said reflector material.

6. (Previously presented) The optoelectronic component as in claim 1, wherein said connecting conductor material contains a metal.

7. (Previously presented) The optoelectronic component as in claim 1, wherein said reflector material contains a metal.

8. (Previously presented) The optoelectronic component as in claim 1, wherein said connecting conductor material contains Au and said reflector material Ag.

9. (Previously presented) The optoelectronic component as in claim 1, wherein said housing body has a cavity in which said semiconductor chip is disposed.

10. (Currently amended) The optoelectronic component as in claim 9, wherein said reflector body is provided with a recess, said recess is part of the cavity of the housing body and said reflector material is disposed on a wall of said recess.

11. (Previously presented) The optoelectronic component as in claim 1, wherein said reflector material is electrically insulated from said connecting conductor material.

12. (Previously presented) The optoelectronic component as in claim 1, wherein an insulation part is disposed between said base part and said reflector part.

13. (Previously presented) The optoelectronic component as in claim 12, wherein said insulation part is preformed separately from said base part and said reflector part.

14. (Currently amended) The optoelectronic component as in claim 9, wherein disposed on said base part, particularly after said reflector part, is an adhesion promoting part provided with a recess that is part of the cavity of said housing body.

15. (Currently amended) The optoelectronic component as in claim 9, wherein disposed in the cavity of said housing body is an envelope that at least partially envelops said semiconductor chip.

16. (Currently amended) The optoelectronic component as in claim 15 ~~4~~, wherein said envelope is arranged at said adhesion promoting part and said envelope adheres better to said adhesion promoting part than it does to said reflector material.

17. (Currently amended) The optoelectronic component as in claim 1, wherein said base part includes a heat sink or wherein the optoelectronic component comprises a thermal contact.

18. (Previously presented) The optoelectronic component as in claim 17, wherein said heat sink is electrically insulated from said semiconductor chip.

19. (Canceled)

20. (New) The optoelectronic component as in claim 12, wherein the insulation part comprises a ceramic.

21. (New) The optoelectronic component as in claim 1, wherein the reflector body is coated with the reflector material.